

Final Product Change Notification

 $202208003F01: {\tt Final Test} and {\tt Burn In Expansion to ASE-CL} ({\tt Taiwan}) for the {\tt FXTH87Exxxx} {\tt Device Family} and {\tt FXTH87Exxx} {\tt Device Family} and {\tt FXTH87Exx} {\tt Device Family} and {\tt Device Famil$

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 12, 2022 Effective date:Nov 10, 2022

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Management summary

NXP is announcing the final test and burn in expansion from the current KES (Malaysia) site to the ASE-CL (Taiwan) site for the FXTH87Exxxx Device Family. The new site will use slightly different shipping labels, reels, and packing for the finished product.

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[X]Packing/Shipping/Labeling	[X]Test Location	[]Electrical spec./Test coverage

[]Firmware []Other

PCN Overview Description

NXP is announcing the final test and burn in expansion from the current KES (Malaysia) site to the ASE-CL (Taiwan) site for the FXTH87Exxxx Device Family. The new site will use slightly different shipping labels, reels, and packing for the finished product.

Reason

Test site expansion using the same test platform to improve manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information Samples are available upon request Production Planned first shipment Nov 07, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality **Data Sheet Revision** No impact to existing datasheet **Disposition of Old Products** Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 11, 2022. **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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NXP Semiconductors

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Affected Part	Affected
Numbers	12NC
FXTH87EH11DT1	935340541528
FXTH87EG02DT1	935340861528
FXTH87EH02DT1	935340862528
FXTH87EH116T1	935340863528
FXTH87EG116T1	935340899528
FXTH87EH118T1	935341038528
FXTH87EH026T1	935341164528
FXTH87EH226T1	935347007528
FXTH87EG11DT1	935351532528
FXTH87EG126T1	935351533528
FXTH87EH12DT1	935351534528
FXTH87EG026T1	935351828528
FXTH87EH126T1	935351829528
FXTH87EH018T1	935376366528
FXTH87EH016T1	935381626528
FXTH87EH219T1	935389706528